


## Full Material Declaration for attached parts list

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Declaration effective from: 1 May 2009 [Approved on 7 March 2016, 12:42 GMT]

## Materials and substances

Use/Location	Material group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	3.00000%	Gold	7440-57-5	8.50000%
			ALUMINIUM	7429-90-5	12.00000%
			Silicon	7440-21-3	79.50000%
Die attach	Gold	4.00000%	Tin	7440-31-5	20.00000%
			Gold	7440-57-5	80.00000%
Encapsulation	EP (Epoxy resin)	68.08000%	Carbon black	1333-86-4	0.30000%
			ANTIMONY TRIOXIDE	1309-64-4	0.80000%
			2,2-Bis(4(2',3'-epoxypropoxy)phenyl)propane	1675-54-3	0.99000%
			Epoxy resin 89	26335-32-0	27.61000%
			Quartz sand	60676-86-0	70.30000%
Inner preparation	Gold	0.14000%	Gold	7440-57-5	100.00000%
Leadfinish	Tin plating	0.68000%	Tin	7440-31-5	100.00000%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	24.10000%	Copper	7440-50-8	100.00000%

## Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOD-323	Diode SMD	0.005	g